
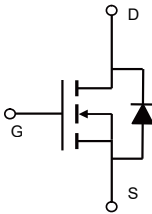


<p>Description</p> <p>These N-Channel enhancement mode power field effect transistors are using split gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.</p> <p>Features</p> <ul style="list-style-type: none"> ◆ 100V,48A, $R_{DS(on),max} = 8.3m\Omega @ V_{GS} = 10V$ ◆ Improved dv/dt capability ◆ Fast switching ◆ 100% EAS Guaranteed ◆ Green device available <p>Applications</p> <ul style="list-style-type: none"> ◆ Motor Drives ◆ UPS ◆ DC-DC Converter 	<p>Product Summary</p> <p>V_{DSS} 100V</p> <p>$R_{DS(on),max} @ V_{GS}=10V$ 8.3mΩ</p> <p>I_D 48A</p> <p>Pin Configuration</p> <div style="display: flex; justify-content: space-around; align-items: center;"> <div style="text-align: center;">  <p>TO-220F</p> </div> <div style="text-align: center;">  <p>Schematic</p> </div> </div>
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Absolute Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	100	V
Continuous drain current ($T_C = 25^\circ C$)	I_D	48	A
Continuous drain current ($T_C = 100^\circ C$)		30	A
Pulsed drain current ¹⁾	I_{DM}	192	A
Gate-Source voltage	V_{GSS}	± 20	V
Avalanche energy ²⁾	E_{AS}	132	mJ
Power Dissipation ($T_C = 25^\circ C$)	P_D	35	W
Storage Temperature Range	T_{STG}	-55 to +150	$^\circ C$
Operating Junction Temperature Range	T_J	-55 to +150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.6	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^\circ C/W$

Package Marking and Ordering Information

Device	Device Package	Marking	Units/Tube
VST10N071-TF	TO-220F	VST10N071-TF	50

Electrical Characteristics
 $T_J = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{GS}=0\text{ V}, I_D=250\mu\text{A}$	100	---	---	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2	3	4	V
Drain-source leakage current	I_{DSS}	$V_{DS}=100\text{ V}, V_{GS}=0\text{V}, T_J = 25^\circ\text{C}$	---	---	1	μA
Gate leakage current, Forward	I_{GSSF}	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	---	---	100	nA
Gate leakage current, Reverse	I_{GSSR}	$V_{GS}=-20\text{ V}, V_{DS}=0\text{ V}$	---	---	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=30\text{ A}$	---	7.4	8.3	$\text{m}\Omega$
Forward transconductance	g_{fs}	$V_{DS}=5\text{ V}, I_D=30\text{ A}$	---	65	---	S
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{DS}=50\text{ V}, V_{GS}=0\text{ V},$ $F=1\text{MHz}$	---	1895	---	pF
Output capacitance	C_{oss}		---	572.5	---	
Reverse transfer capacitance	C_{rss}		---	11.8	---	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=50\text{V}, V_{GS}=10\text{V}, I_D=30\text{A}$	---	16.6	---	ns
Rise time	t_r		---	20	---	
Turn-off delay time	$t_{d(off)}$		---	68	---	
Fall time	t_f		---	20.8	---	
Gate resistance	R_g	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, F=1\text{MHz}$	---	1.7	---	Ω
Gate charge characteristics						
Gate to source charge	Q_{gs}	$V_{DS}=50\text{ V}, I_D=50\text{A},$ $V_{GS}=10\text{ V}$	---	10	---	nC
Gate to drain charge	Q_{gd}		---	4.2	---	
Gate charge total	Q_g		---	28.3	---	
Drain-Source diode characteristics and Maximum Ratings						
Continuous Source Current	I_S		---	---	48	A
Pulsed Source Current ³⁾	I_{SM}		---	---	192	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0\text{V}, I_S=30\text{A}, T_J=25^\circ\text{C}$	---	0.9	---	V
Reverse Recovery Time	t_{rr}	$I_S=30\text{A}, di/dt=100\text{A}/\mu\text{s},$ $T_J=25^\circ\text{C}$	---	50	---	ns
Reverse Recovery Charge	Q_{rr}		---	72	---	nC

Notes:

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2: $V_{DD}=50\text{V}, V_{GS}=10\text{V}, L=0.5\text{mH}, I_{AS}=23\text{A}, R_G=25\Omega,$ Starting $T_J=25^\circ\text{C}$.
- 3: Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

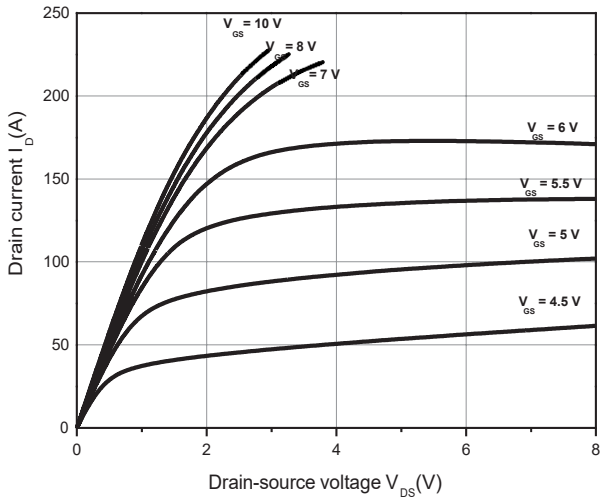
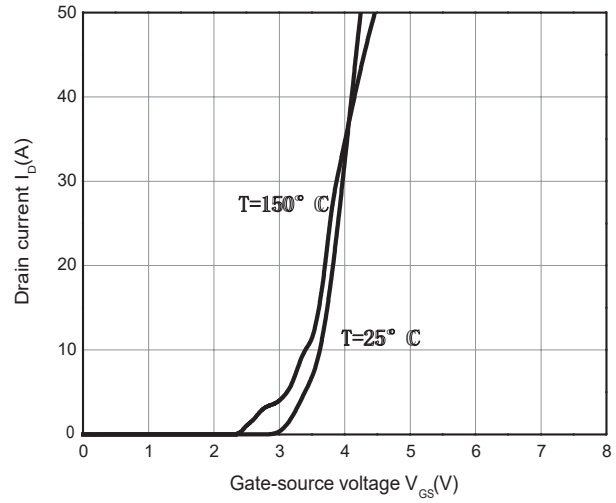
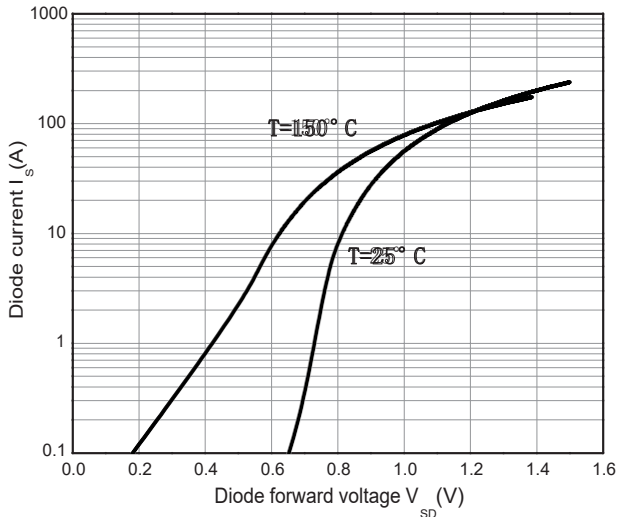
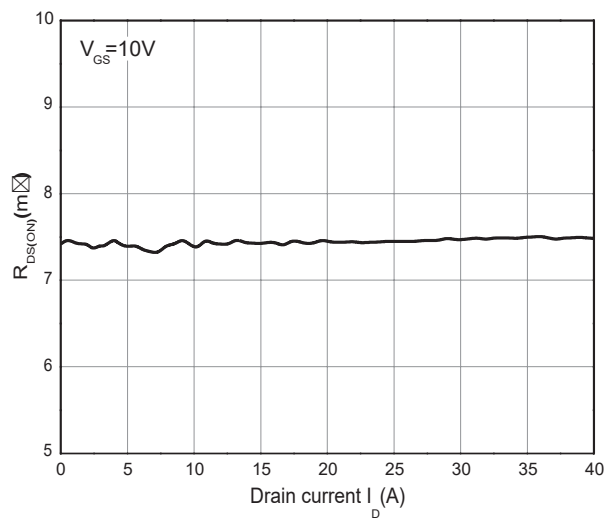
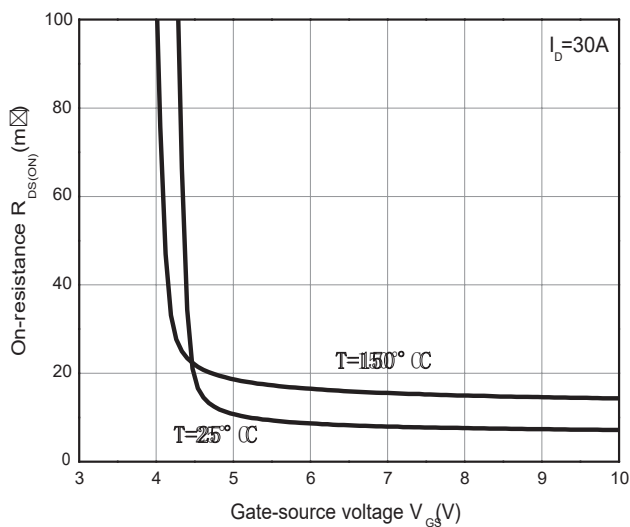
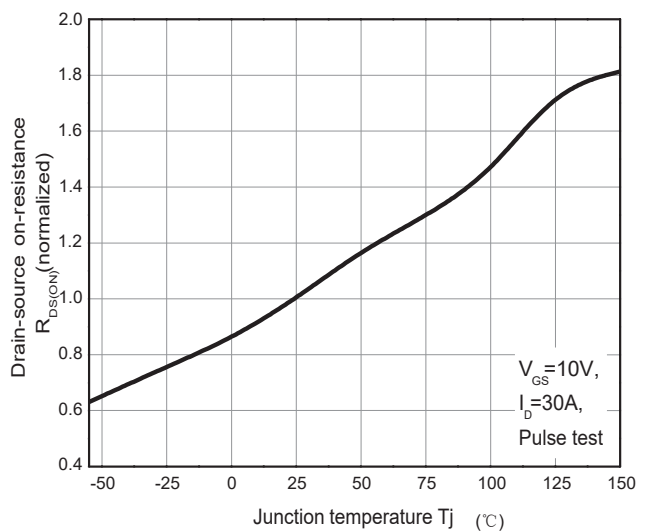
Electrical Characteristics Diagrams
Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics

Figure 3. Body-Diode Characteristics

Figure 4. On-Resistance Variation vs. Drain Current

Figure 5. Rds(on) vs. Gate Voltage

Figure 6. On-Resistance vs. Temperature


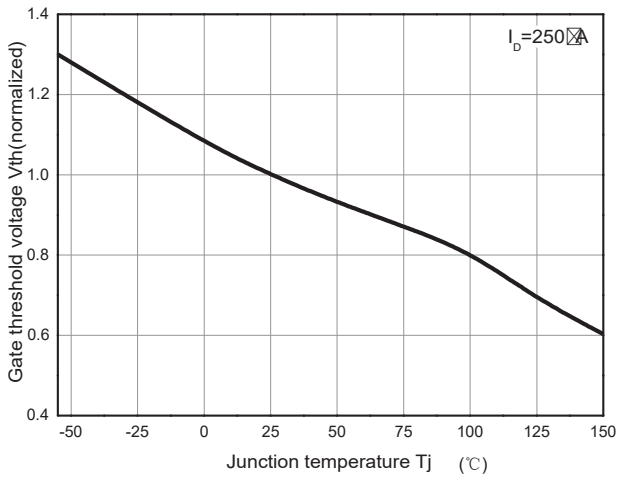
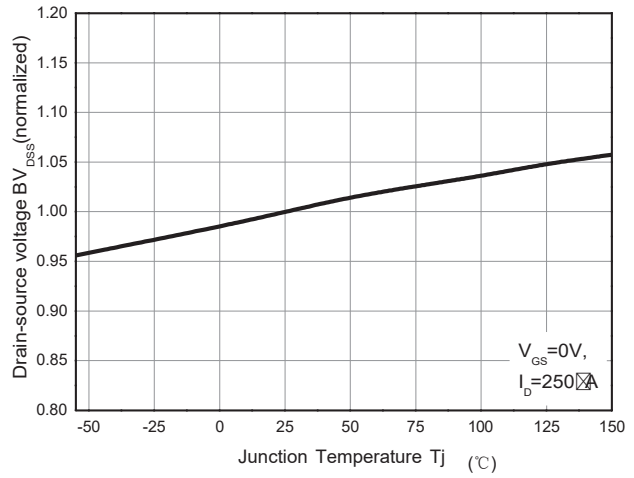
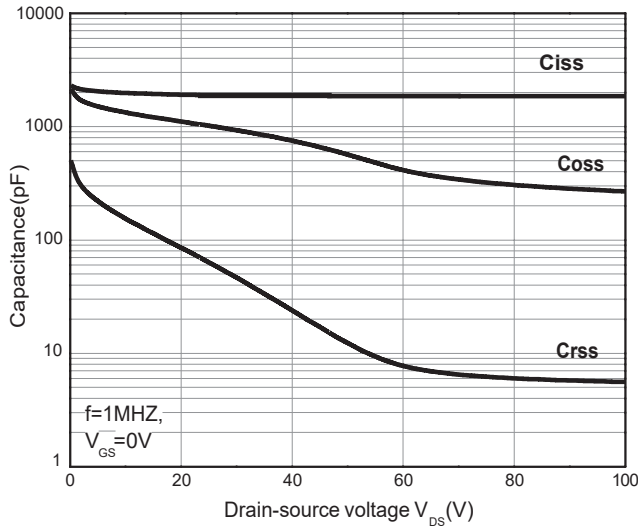
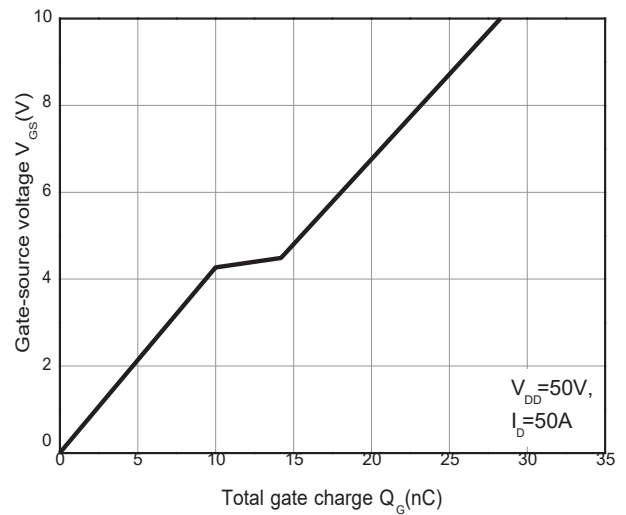
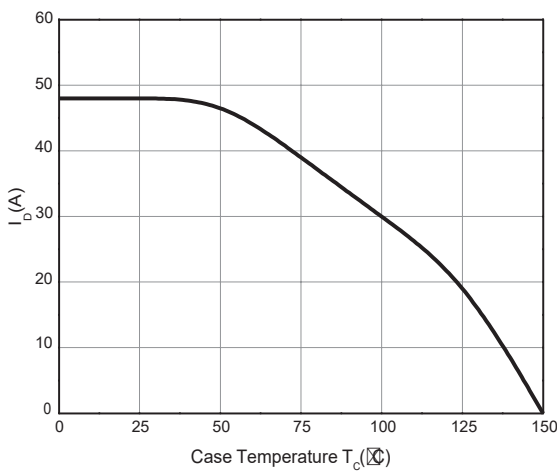
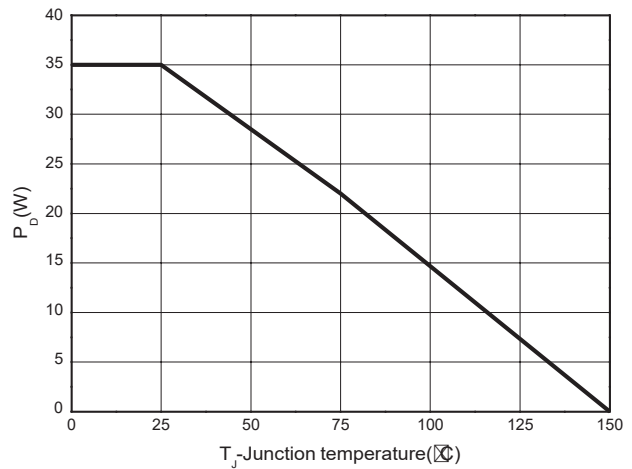
Figure 7. Threshold Voltage vs. Temperature

Figure 8. Breakdown Voltage vs. Temperature

Figure 9. Capacitance Characteristics

Figure 10. Gate Charge Characteristics

Figure 11. Drain Current Derating

Figure 12. Power Dissipation vs. Temperature


Figure 13: Safe Operating Area

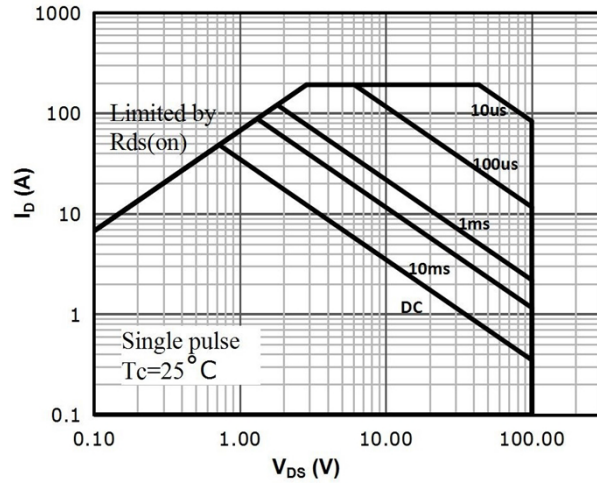
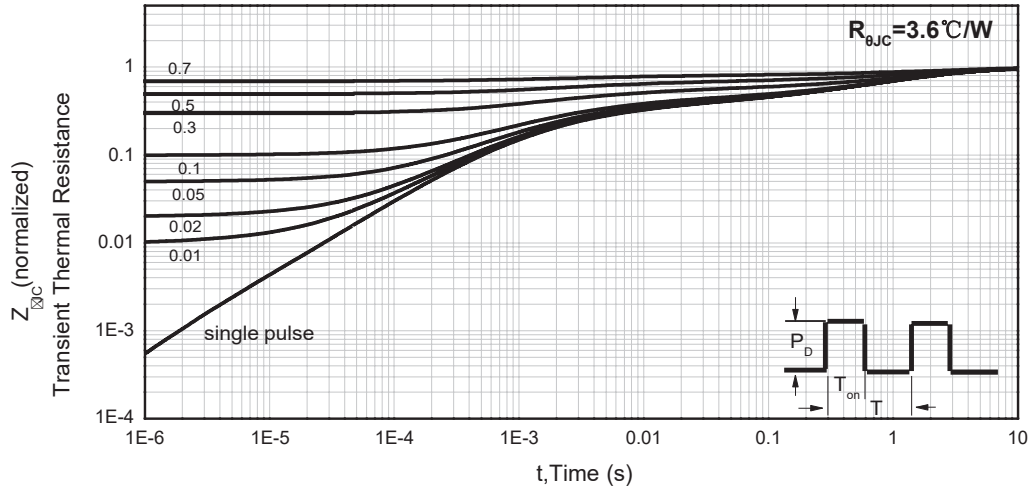


Figure 14. Normalized Maximum Transient Thermal Impedance (RthJC)



Test Circuit & Waveform

Figure 15. Gate Charge Test Circuit & Waveform

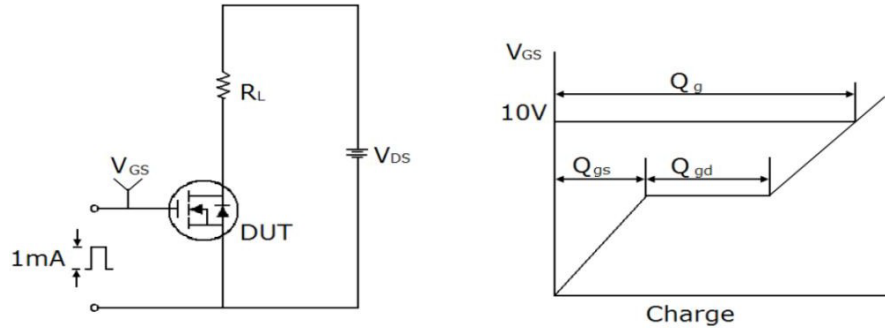


Figure 16. Resistive Switching Test Circuit & Waveform

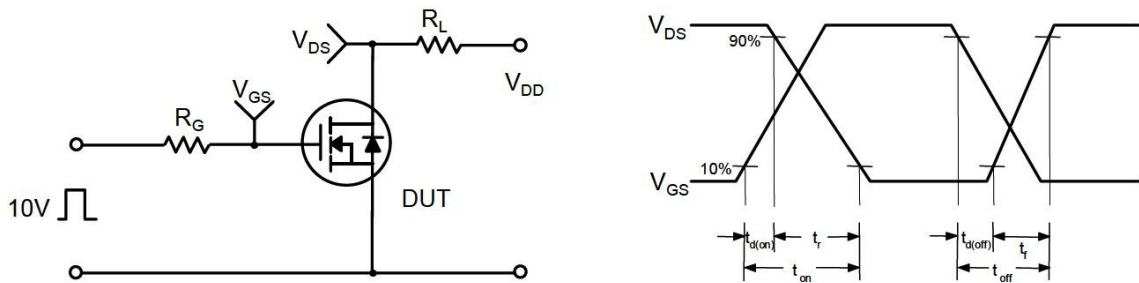


Figure 17. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

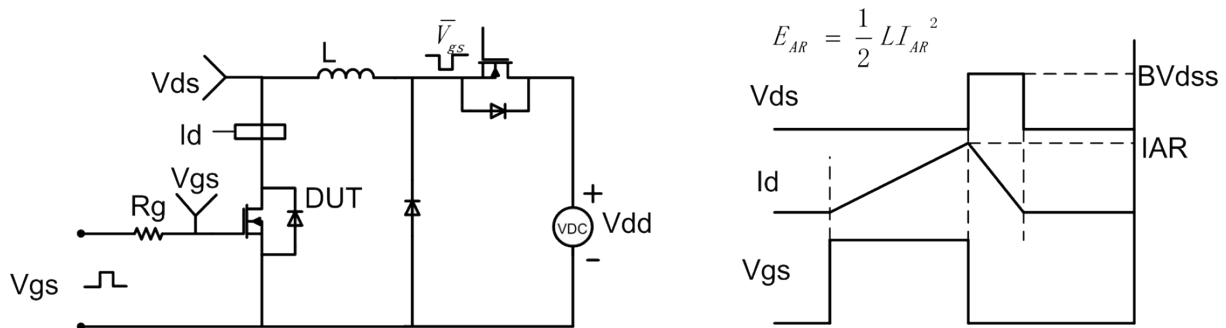


Figure 18. Diode Recovery Circuit & Waveform

